

Notice of References Cited

Application/Control No.

09/943,196

Applicant(s)/Patent Under
Reexamination
MAY, CHARLES E.

Examiner

Lynette T. Umez-Eronini

Art Unit

1765

Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5780358	07-1998	Zjou et al.	438/645
	B	US-5318927	06-1994	Sandhu et al.	438/3
	C	US-5869392	02-1999	Kimura	438/620
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N	JP-08330262-A	12-1966	Japan	Muroyama	H01L 21/304
	O	JP-2001139935-A	05-2001	Japan	Ri et al.	H01L 21/304
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Muroyama et al., Slurry for Polishing and Manufacture of Semiconductor Device, December 13, 1996, English Abstract of JP 08330262 A2, 2 pp.
	V	Muroyama et al. Slurry for Polishing, and Manufacture of Semiconductor Device, December 13, 1996, Computer translation of JP 08330262 A, 5 pp.
	W	Ri et al., Composition for Polishing, May 22, 2001, English Abstract of JP 20001139935-A, 1 page.
	X	Ri et al., Composition for Polishing, May 22, 2001, Computer translation of JP 20001139935-A into English, 8 pp.

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.